Noise

•What is NOISE? <u>A</u> definition:

Any unwanted signal obscuring signal to be observed

two main origins



•EXTRINSIC NOISE examples...

pickup from external sources unwanted feedback
 RF interference from system or elsewhere, power supply fluctuations
ground currents
 small voltage differences => currents can couple into system

may be hard to distinguish from genuine signalsbutAVOIDABLEAssembly & connections, especially to ground, are important

•INTRINSIC NOISE

Fundamental property of detector or amplifying electronics Can't be eliminated but can be MINIMISED

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Origins of noise in amplifying systems

•1. Thermal noise

Quantum-statistical phenomenon

Charge carriers in constant thermal motion macroscopic fluctuations in electrical state of system

•2. Shot noise

Random fluctuations in DC current flow originates in quantisation of charge non-continuous current

•3. 1/f noise

Characteristic of many physical systems least well understood noise source *commonly associated with interface states in MOS electronics*

Thermal noise (i)

•Einstein (1906), Johnson, Nyquist (1928) e.g. resistor: $\sim 10^{23}$ possible states macroscopic statistical average over micro-states •Experimental observation Mean voltage <v> = 0 $\langle v^2 \rangle = 4kT.R.$ f f = observing bandwidth Variance $(v) = \langle v^2 \rangle = 1.3 \ 10^{-10} \ (R. \ f)^{1/2}$ volts at 300K gaussian distribution of fluctuations in v e.g. R = 1M f = 1Hz $(v) = 0.13\mu V$ Noise power = 4kT. f independent of R & q independent of f - WHITE •Quantum effects Normal mode energies: $kT = hf/(e^{hf/kT} - 1)$ $kT \gg hf$

at 300° K kT = 0.026 eV hf = kT at f = 6.10¹² Hz

Thermal noise (ii)



Noise generator + noiseless resistance R

•Spectral densities

mean square noise voltage or current per unit frequency interval

 $w_V(f) = 4kTR$ (voltage) $w_I(f) = 4kT/R$ (current)

•Why not infinite fluctuation in infinite bandwidth?

- A-1: QM formula -> 0 at high f
- A-2: real components have capacitive behaviour (high f)
- or inductive (low f).

with R and C in parallel $\langle v^2 \rangle = kT/C$





Shot noise

•Poisson fluctuations of charge carrier number

eg arrival of charges at electrode in system - induce charges on electrode



•Examples

electrons/holes crossing potential barrier in diode or transistor electron flow in vacuum tube

$$\langle i_n^2 \rangle = 2qI.$$
 f WHITE
I = DC current

(NB notation e = q)

gaussian distribution of fluctuations in i

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1/f noise

•White noise sources frequently dominate in many real systems however frequency dependent noise is also common

•1/f noise is a generic term for a wide range of phenomena, possibly not always related



pMOS transistor noise spectrum

An explanation for 1/f noise

•Silicon MOS transistors are very sensitive to oxide interface typically populated by band-gap energy levels (traps) traps exchange charge with channel - ie. emit and capture electrons or holes •Traps have lifetime to retain charge $h(t) \sim e^{-t/}$ Expect a range of traps with different time constants, distributed with p() in frequency domain $H() \sim 1/(1+j)$

Deduce frequency spectrum by integrating over all values of

 $w(f) \sim {}_{0} p() |H()|^{2}d$

If p() = constant, ie all time constants equally probable

w(f) ~ $_0$ d /(1 + 2 2) [standard integral, put tan =] = A/f

Many other real-life processes have $e^{-t/}$ time distributions -

typical of random, Poisson-type processes

Campbell's theorem - time domain



Campbell's theorem - frequency domain

•Recall relationship between impulse response h(t) and transfer function H() H() = $\int_{-}^{-} h(t) e^{-j t} dt$ h(t) = $\int_{-}^{-} H() e^{-j t} df$ H() = $v_{out}() / v_{in}()$

•Rewrite (B) using Parseval's Theorem

$$\int_{-} h^{2}(t) dt = |H()|^{2} df = 2 \int_{0} |H()|^{2} df$$

$$h(t) \text{ is real and thus}$$

$$H(-) = H^{*}()$$

so ${}^{2} = n \int_{-}^{-} h^{2}(t) dt = n \int_{-}^{-} |H()|^{2} df$

This relates noise spectral densities at input and output:

 $w_{out}(f) = w_{in}(f) |H()|^2$ can use theorem to calculate system response to noise

•eg. shot noise Consider impulse response to be impulse (ie unchanged!)

$$h(t) = e(t) \implies H() = 1.e$$

$$^{2} = n e^{2} \int_{-\infty}^{-\infty} (t) dt = ne^{2} \int_{-\infty}^{-\infty} |H(t)|^{2} dt = 2ne^{2} f$$

but
$$n = I/e \implies 2 = 2eI f$$

Amplifier systems for spectroscopy

•typical application - precise measurements of x-ray or gamma-ray energies



•fast amplifier and logic -

start ADC ("gate") and flag interesting "events" to DAQ system

- most signals arrive randomly in time.

Other logic required to maximise chance of "good" event, eg second detector

"Rules" of low noise amplifier systems

•Combine <u>uncorrelated</u> noise sources in quadrature

 $e_{tot}^2 = e_1^2 + e_2^2 + e_3^2 + \dots + i_n^2 R^2 + \dots$

follows from Campbell's theorem

consider as combinations of gaussian distributions

• First stage of amplifier dominates

noise originates at input

•Noise is independent of amplifier gain or input impedance so noise can be referred to input

•In real systems both are approximations - but normally good ones so often sufficient to focus on input device

Amplifiers - dominance of input stage



Amplifier systems (and amplifiers!) usually consist of several stages
 impractical to put all gain at one location - power, heating, material, size,...
 Calculate signal and noise at output

$$\begin{split} \mathbf{S}_{out} &= \mathbf{G}_1.\mathbf{G}_2.\mathbf{G}_3\mathbf{S}_{in} & \text{for 3 stage system, but can easily extend to N} \\ (\mathbf{e}_{out})^2 &= \mathbf{G}_1^2.\mathbf{G}_2^2.\mathbf{G}_3^2\mathbf{e}_1^2 + \mathbf{G}_2^2.\mathbf{G}_3^2\mathbf{e}_2^2 + \mathbf{G}_3^2\mathbf{e}_3^2 \\ (\mathbf{e}_{out}/\mathbf{S}_{out})^2 &= (\mathbf{e}_1^2 + \mathbf{e}_2^2/\mathbf{G}_1^2 + \mathbf{e}_3^2/\mathbf{G}_1^2.\mathbf{G}_2^2)/\mathbf{S}_{in}^2 \end{split}$$

•Desirable to maximise gain at input stage

eg stage 1 boosts signal enough for transmission down cable and should be large enough that environmental noise is not significant

Amplifiers - location of noise sources

•Normal to partition noise sources not fundamental to calculations *but can simplify!*



•Parallel noise sources appear as currents at input

- detector leakage current
- bias resistors
- feedback resistor



Amplifiers - reference to input



assume: signal source and associated impedance noise sources amplifier with gain & input impedance

noise at output E_{no²} = A² {e²_nZ²_{in}/(Z_{in} + R_s)² + i²_nR²_sZ²_{in}/(Z_{in} + R_s)² }
transfer function K = V_{out}/V_{in} = A.V_{sig}.Z_{in}/(Z_{in} + R_s)V_{sig} = AZ_{in}/(Z_{in} + R_s)

• noise at input $E_{ni}^2 = E_{no}^2/K^2 \implies E_{ni}^2 = e_n^2 + i_n^2 R_s^2 \qquad no Z_{in} \text{ or A dependence}$

easy to show analogous result $I_{ni}^2 = i_n^2 + e_n^2 / R_s^2$ choice is for convenience

in most detector systems, there is a current signal source and a parallel capacitancethen the spectral distribution of noise at the input is affected

 $I_{ni}^2 = i_n^2 + e_n^2 \omega^2 C^2$ <u>no longer white</u>

Real amplifiers

•The first amplifier stage dominates - reason for distinction of pre-amplifier most low-noise amplifiers are based on very simple concepts



within the preamplifier we expect the input device to be the most important
•To understand noise performance we need to study input device bipolar or FET

Bipolar transistor noise



Fluctuations in I_c $i_c^2 = 2eI_c$ f Fluctuations in I_B $i_b^2 = 2eI_B$ f but these are correlated since I_B $I_c/$ • <u>Thermal noise</u> in base & contacts $e_b^2 = 4kTr_b$ f $r_b = base$ spreading resistance

•Transfer noise sources to input

use $v_{be} = i_c r_e = (kT/qI_c)i_c$

 $e_n^2 = (4kTr_b + 2qI_cr_e^2) f = [4kTr_b + 2(kT)^2/qI_c] f$

 $i_n^2 = 2eI_B f$



•The constraint that i_n^2 , e_n^2 are correlated gives a limited range of noise with best performance for high speed applications

Some useful numerical values

kT/e 0.025 V = 25 mV at 293K (Room temperature) e = 1.6 10⁻¹⁹ coulomb

•Parallel noise - what resistor is equivalent to given current?

$$4kT/R_{p} = 2eI$$

I = 2(kT/e)(1/R_p) = 50mV/R

eg, 1M 50nA

•Parallel noise spectral density - units and magnitudes

$$i_n = [2eI_B]^{1/2} = [32e^{-18}I_B]^{1/2} = 0.6I_B^{1/2} nA/\sqrt{Hz}$$

eg, 3A 1nA/ Hz 3µA 1pA/ Hz

•Series noise spectral density - units and magnitudes

$$e_n = [4kTR_s]^{1/2} = [4(kT/e)eR]^{1/2} = [1.6 \ 10^{-20}R]^{1/2} = 0.13R^{1/2} \ nV/\sqrt{Hz}$$

•r _b is often small so neglect			
b	Ŭ	$I_{\rm C} = 1 {\rm mA}$	$I_{\rm C} = 100 \mu A$
	= 100	$I_{B} = 10 \mu A$	$I_B = 1\mu A$
		•	- •
	$e_n = [2(kT)^2/qI_c]^{1/2}$	0.45 nV/ Hz	1.4 nV/ Hz
	$= [2(kT/q)^{2}(q/I_{C})]^{1/2}$		
	$\mathbf{i}_{n} = \left[2\mathbf{q}\mathbf{I}_{B} \right]^{1/2}$	1.8 pA/ Hz	0.6 pA/Hz
	$i_n R_s$ for $R_s = 1k$	1.8 nV/ Hz	0.6 nV/Hz
	$[4kTR_S]^{1/2}$ for $R_S=1k$	4.0 nV/ Hz	4.0 nV/ Hz
	NF for R _S = 1k	0.84 dB	0.59 dB

•Noise figure - often used to characterise voltage amplifier performance NF [dB] = 10log₁₀(Total noise power at input/Source noise power)

$$=10\log_{0}\left(\frac{e_{n}^{2}+i_{n}^{2}R_{s}^{2}+4kTR_{s}}{4kTR_{s}}\right) =10\log_{0}\left(1+\frac{e_{n}^{2}+i_{n}^{2}R_{s}^{2}}{4kTR_{s}}\right)$$

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•Gate current <u>shot noise</u>

 $i_g^2 = 2eI_G f$ <u>negligibly small</u> for most applications

high impedance of gate oxide (insulator) to substrate

•<u>Thermal noise</u> inside the transistor

thermal <u>current</u> fluctuations in channel (- but **not** shot)

$$i_d^2 = (4kT/R_n)$$
 f = $4kT(2/3)g_m$ f

$$1/f$$
 noise $e_n^2 A/f$

•Transfer noise sources to input

 $i_d = g_m v_{gs} = > e_n^2 = i_d^2 / g_m^2$ $e_n^2 = [4kT(2/3g_m) + A/f] f$ $i_n^2 = 0$



 i_n^2

MOSFET thermal noise

• Parameters are (almost) controlled by geometry and current alone

 $g_{m} = [2\mu C_{ox}(W/L)I_{DS}]^{1/2}$ $C_{ox} = _{ox}/t_{ox}$ $e_{n}^{2} = 4kT(2/3g_{m})$ f ~ $1/g_{m}$

•How to get large g_m ?

Increase I_{DS} - but $e_n \sim I^{-1/4}$ power is a concern

Increase C_{ox} - it scales with technology feature size so modern processes help

1980 ~10 μm 2000 ~ 0.25 μm for L_{min} $~0.25 \mu m$ t_{ox} ~ 5 nm

Make W/L large

W can be made very large, eg 2-3mm

L can be minimum feature size

Cooling - can gain small amount - but device heats

•Caveat carrier mobility μ - unfortunately not a constant

carriers typically approach saturation velocity at high electric fields

 $1V/0.25\mu m = 4x10^4 V/cm$ so $\mu = v/E$ falls as transistors shrink

MOSFET 1/f noise

 $\bullet e_{1/f}^2 \quad A_f/f$

 $A_f K_f / [WL(C_{ox})^2]$

 $K_{\rm f}$ is technology dependent $~~K_{\rm f} \sim 10^{-30}$ - $10^{-32}~C.cm^{-2}$

PMOS transistors are significantly better than NMOS

•Corner frequency

 $\label{eq:corner} f_{corner} \ \ where \ e_{thermal} \ = \ e_f \quad typically \ \sim 10\ -1000 kHz$ dependent on technology details, device dimensions

JFET Noise

•Almost identical to MOSFET

•- differences are

Negligible 1/f noise - channel is buried below surface

Small gate current - gate is p-n diode

both can be reduced by cooling

• JFET is interesting for high resolution spectroscopy allows to employ long shaping time constants (low f) because of the very low 1/f noise

• Noise sources referred to input

$$e_n^2 = 4kT(2/3g_m)$$
 f
 $i_n^2 = 2eI_g$ f

